



Advanced Product Change Notification

202103036A : TSSOP8 (SOT505-1) Assembly Expansion in ATBK and Manufacturing Alignment

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 28, 2021

Dear Emma Tempest,



Here is your personalized notification about a NXP general announcement.

For detailed information we invite you to [view this notification online](#)

Management summary

SOT505-1 assembly will be discontinued at ATP and ATBK is adding SOT505-1 assembly to maintain supply.

Change Category

| | | | | |
|--|--|---|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input checked="" type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware <input type="checkbox"/> Other | | | | |

PCN Overview

Description

NXP is expanding ATBK assembly capabilities to include the part types in the attached file list. Mold compound and die adhesive materials in the ATBK manufacturing process will use the standard EMC-7470L-Q and QMI519 materials respectively. Additionally, ATBK will employ a roughened leadframe as a package quality improvement to reduce delamination. NXP has extensive manufacturing capabilities in the TSSOP8 family and with the critical demand for these products, these changes will help with timely deliveries.

Reason

Due to increasing demand for SOT505-1 packaged devices, NXP is adding the ATBK flow as an alternate source to help provide timely deliveries.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from Jul 01, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

The Self Qualification Report will be ready on Aug 02, 2021.

The Final PCN is planned to be issued on: Sep 15, 2021.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 28, 2021.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

| | |
|-----------------------|--|
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NXP Quality Management Team.

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